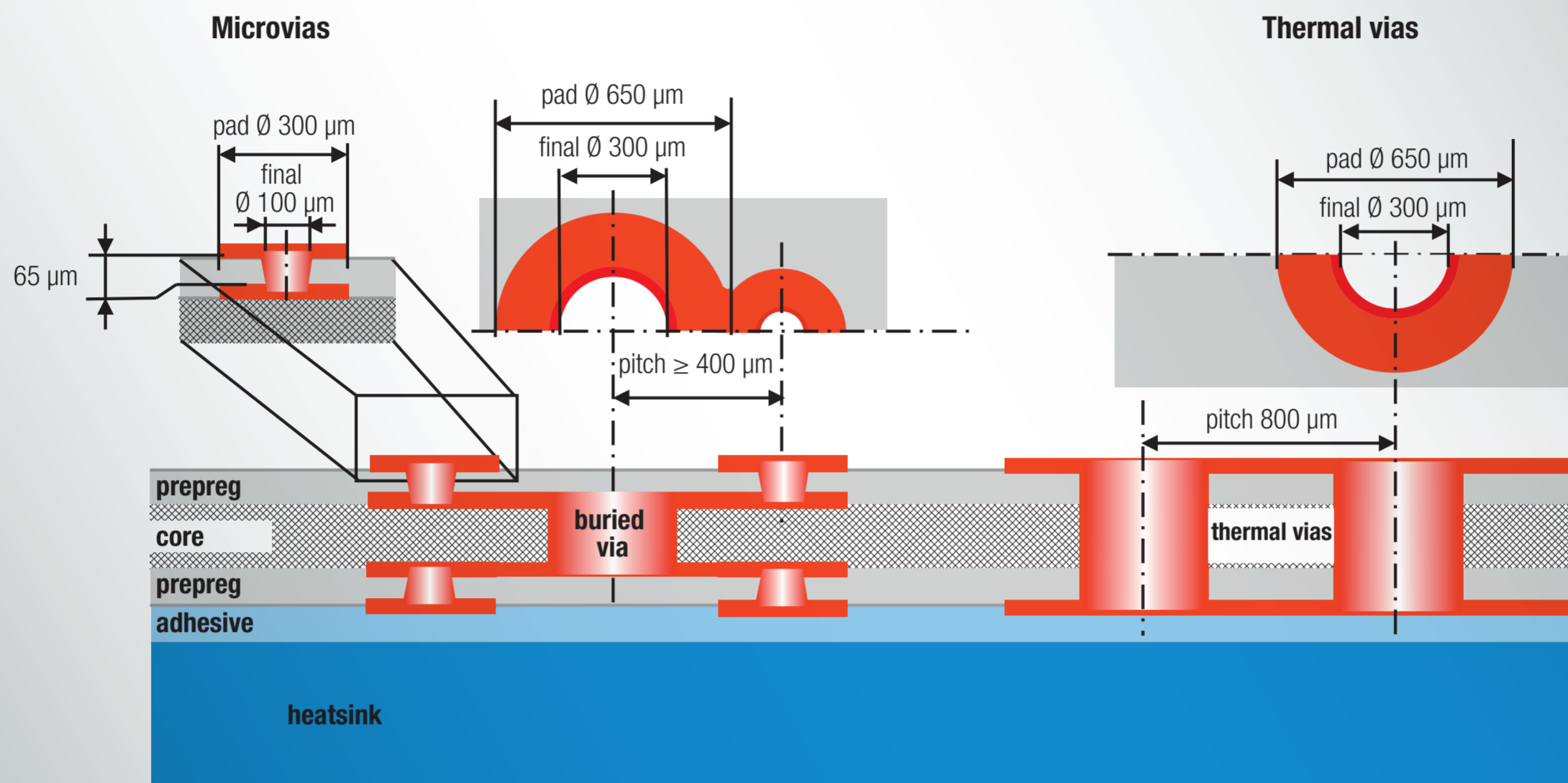


Thermal Management Design Guide



Standard Design Rules



Combination microvia, buried via as thermal vias

Thermal vias filled (filled & capped via type 7)

Heatsink breaking points, micro edges

Positive micro edges
The breaking point is located in the rout path outside the PCB outline.

Negative micro edges
Breaking point inside the PCB outline. To ensure stability of the panel additional ribs are required.

Thermal simulation

Printed circuit board 2 layer, 1,6 mm, improved layout, without thermal vias

Printed circuit board 2 layer, with heat sink, 1,6 mm, improved layout, with thermal vias

Thermal simulation of the printed circuit board can help to select the best printed circuit board construction and the optimal layout.